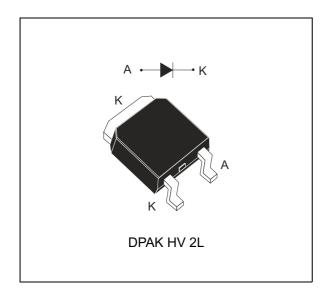
STPSC6H12



1200 V power Schottky silicon carbide diode

Datasheet - production data



Features

- High frequency free-wheel / boost diode
- Robust high-voltage periphery
- Ultrafast high voltage switching independent of temperature

Description

ST's 1200 V high-performance rectifier is specifically designed to be used in photo-voltaic inverters or in applications where negligible switching losses are required.

The STPSC6H12 helps to increase the application efficiency yield by up to 2% thanks to its ability to work at high frequency whatever the temperature.

The central lead of the DPAK package is removed to meet the IEC60664 and UL 840 standard requirements for a higher voltage.

These characteristics make it the best-in-class 1200 V diode.

Table 1. Device summary

Symbol	Value
I _{F(AV)}	6 A
V_{RRM}	1200 V
T _j (max.)	175 °C
V _F (6 A, 25 °C) typ.	1.55 V
C _j (300 V) typ.	30 pF

Characteristics STPSC6H12

1 Characteristics

Table 2. Absolute ratings (limiting values at 25 °C unless otherwise specified)

Symbol	Par	Value	Unit	
V_{RRM}	Repetitive peak reverse voltage		1200	V
I _{F(RMS)}	Forward rms current		11	Α
I _{F(AV)}	Average forward current $T_c = 125$ °C, $\delta = 0.5$, DC		6	Α
I _{FSM}	Surge non repetitive forward	$t_p = 10 \text{ ms sinusoidal}, T_c = 25 \text{ °C}$		
	current	$t_p = 10 \text{ ms sinusoidal}, T_c = 150 ^{\circ}\text{C}$	30	Α
	Current	100		
I _{FRM}	Repetitive peak forward current $\delta = 0.1$, $T_c = 125$ °C		28	Α
T _{stg}	Storage temperature range		-65 to +175	°C
Tj	Operating junction temperature range ⁽¹⁾		-40 to +175	°C

^{1.} $\frac{dPtot}{dT_j} < \frac{1}{Rth(j-a)}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

Symbol	Parameter	Тур.	Max.	Unit
R _{th(j-c)}	Junction to case	1.3	1.9	°C/W

Table 4. Static electrical characteristics

Symbol	Parameter	Tests conditions		Min.	Тур.	Max.	Unit
I _R ⁽¹⁾	Reverse leakage	T _j = 25 °C	\/ \/	-	100	400	μΑ
current	T _j = 150 °C	$V_R = V_{RRM}$	-	0.65	1.5	mA	
V_ (2)	V _F ⁽²⁾ Forward voltage drop	T _j = 25 °C	I _F = 6 A	-	1.55	1.9	V
VF`′		T _j = 150 °C	IF = 0 A	-	2.05	2.6	,

^{1.} $t_p = 10 \text{ ms}, \delta < 2\%$

To evaluate the conduction losses use the following equation:

$$\mathsf{P} = 0.89 \; \mathsf{x} \; \mathsf{I}_{\mathsf{F}(\mathsf{AV})} + 0.285 \; \mathsf{x} \; \mathsf{I}_{\mathsf{F}^2(\mathsf{RMS})}$$

Table 5. Dynamic electrical characteristics

Symbol	Parameter	Test conditions	Тур.	Unit
Q _{cj} ⁽¹⁾	Total capacitive charge	V _R = 800 V	29	nC
C _j Total capacitance	$V_R = 0 \text{ V}, T_c = 25 \text{ °C}, F = 1 \text{ MHz}$	330	pF	
		$V_R = 300 \text{ V}, T_C = 25 \text{ °C}, F = 1 \text{ MHz}$	30	ρι

^{1.} Most accurate value for the capacitive charge: $Q_{cj} = \int_{0}^{V_{cj}(V_R) \cdot dV_R} dV_R$

^{2.} $t_p = 500 \ \mu s, \ \delta < 2\%$

STPSC6H12 Characteristics

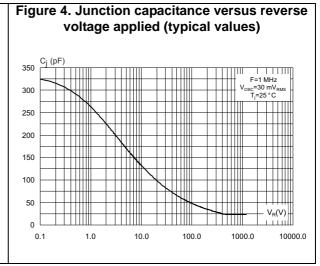
Figure 1. Forward voltage drop versus forward current (typical values)

2.0

1.E+03 1.E+02 1.E+01 1.E-01 1.E-03 0 100 200 300 400 500 600 700 800 900 1000 1100 1200

Figure 2. Reverse leakage current versus

Figure 3. Peak forward current versus case temperature 40 30 20 δ = 0.5 $\delta = 1$ $T_{C}(^{\circ}C)$ 0 25 50 75 100 125 150 175



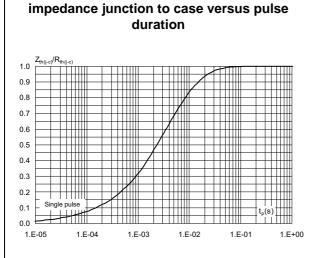


Figure 5. Relative variation of thermal

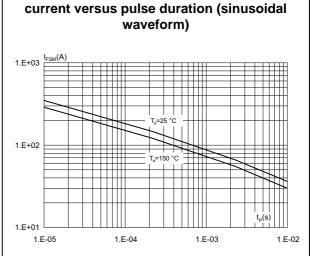


Figure 6. Non-repetitive peak surge forward

Characteristics STPSC6H12

0 1

30 Q_{cj}(nC)
25 20 15 10 5

V_R (V)

700

Figure 7. Total capacitive charges versus reverse voltage applied (typical values)

2 Package information

- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

2.1 DPAK HV 2L package information

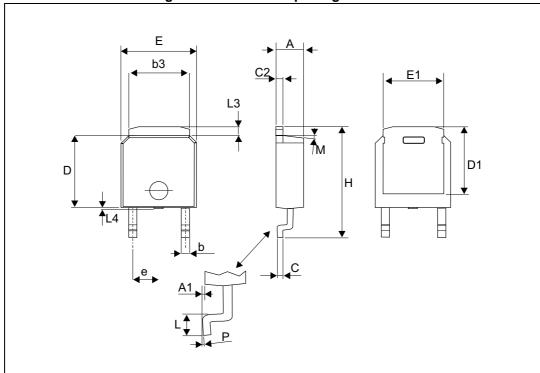


Figure 8. DPAK HV 2L package outline

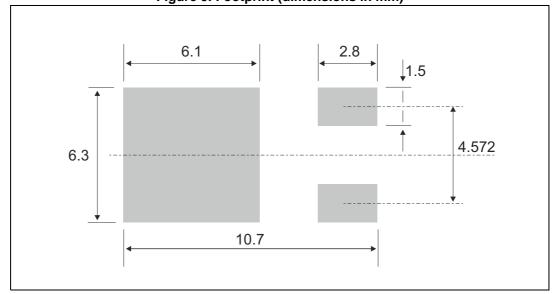
Package information STPSC6H12

Table 6. DPAK HV 2L package mechanical data

	Dimensions						
Ref.	Millimeters				Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	2.16	2.29	2.40	0.085	0.090	0.094	
A1	0.06	0.08	0.13	0.002	0.003	0.005	
b	0.71	0.76	1.07	0.028	0.029	0.030	
b3	5.004	5.10	5.21	0.197	0.201	0.205	
С	0.46	0.51	0.56	0.018	0.020	0.025	
c2	0.76	0.81	0.86	0.029	0.032	0.034	
D	5.97	6.10	6.22	0.235	0.240	0.245	
D1	5.84 REF			0.230 REF			
E	6.48	6.60	6.73	0.255	0.260	0.265	
E1	4.95	5.08	5.21	0.195	0.200	0.205	
е		2.29 REF 0.90 REF					
Н	9.70	9.83	10.08	0.382	0.387	0.397	
L	1.02	1.14	1.40	0.040	0.045	0.055	
L3			1.14			0.045	
L4 ⁽¹⁾	0.000		0.15	0.000		0.006	
М		7°			7°		
Р			5°			5°	

^{1.} Maximum plastic protrusion

Figure 9. Footprint (dimensions in mm)



3 Ordering information

Table 7. Ordering information

Order code Marking		Package	Weight	Base qty	Delivery mode
STPSC6H12B-TR1	STPSC 6H12	DPAK HV 2L	0.368g	2500	Tape and reel

4 Revision history

Table 8. Document revision history

Date	Revision	Changes
02-Aug-2013	1	First issue.
05-Aug-2013	2	Corrected typographical error in Table 7.
13-Mar-2015	3	Updated marking information in Table 7: Ordering information.
06-May-2015	4	Updated cover page. Format updated to current standard.
01-Sep-2016	5	Updated cover image and <i>Figure 8</i> .

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